Session Q:

Microwave Packaging and Manufacturing

Chairman: Douglas Maki
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This session's papers cover a broad range of packaging and manufacturing issues from modeling through testing and yield analysis. The session begins with a novel approach to thermal management through phase change mechanisms from AEL followed by papers on resonant field measurements on microwave housings and a low cost method of injection molding complex packages. A statistical approach to test strategy is presented by TRW that can significantly reduce the overall cost of MMICs. Finally, a paper from Pacific Monolithics describes the performance and yield of a 5-bit X-band phase shifter gathered from measurements on thousands of circuits.

3:30 p.m.–5:00 p.m., Tuesday, May 8, 1990
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